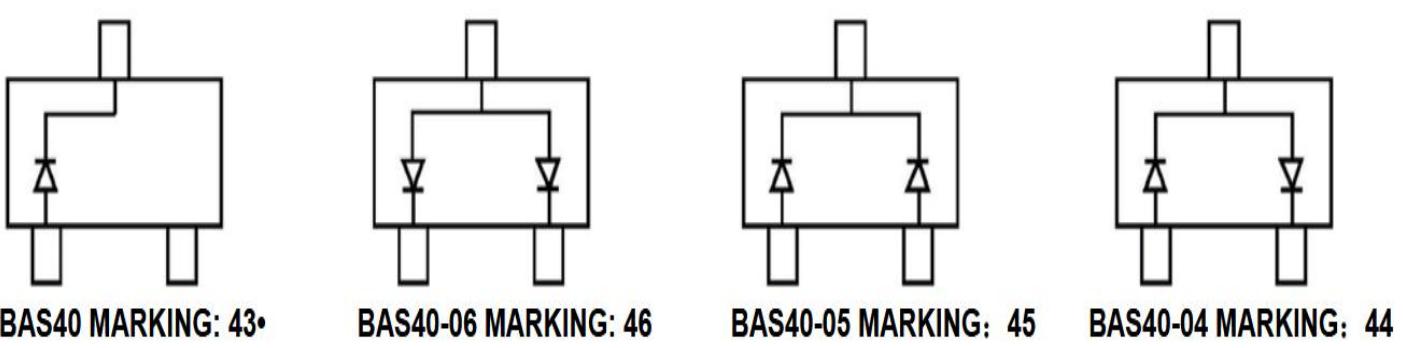
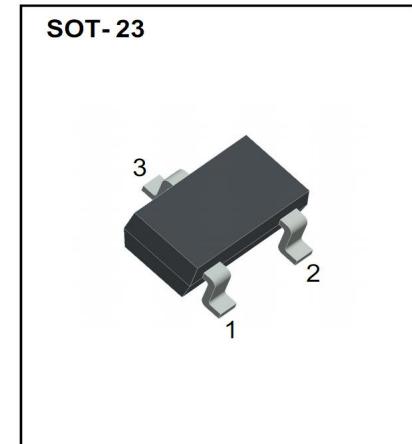


## SOT-23 Plastic-Encapsulate Diodes

**BAS40/-04/-05/-06**
**Schottky Diodes**
**FEATURES:**

- Low Forward Voltage
- Fast Switching



**Solid dot = Green molding compound device, if none, the normal device.**

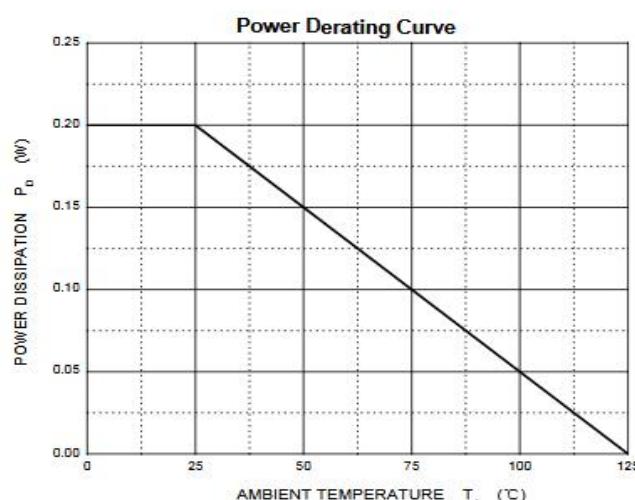
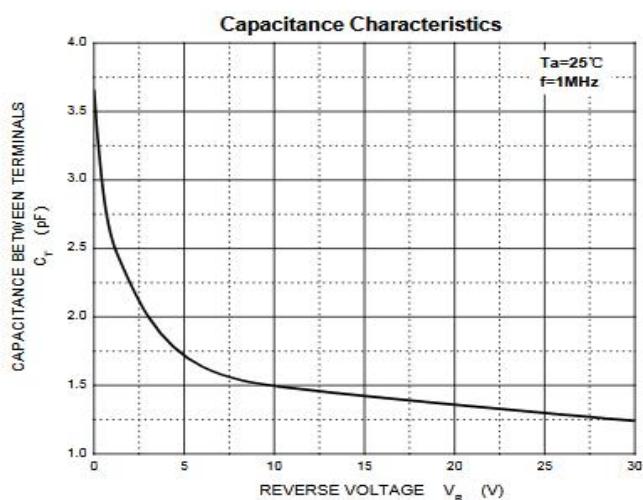
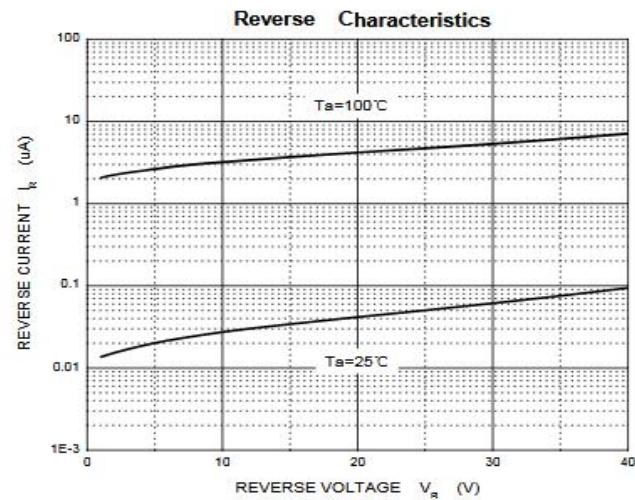
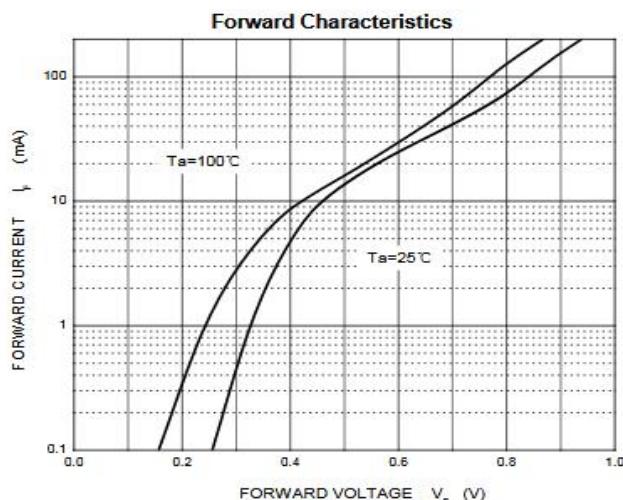
**Maximum ratings (@Ta=25°C)**

Parameter	Symbol	Limit	Unit
Peak Repetitive Reverse Voltage	VRRM	40	V
Working Peak Reverse Voltage	VRWM	40	V
DC Blocking Voltage	VR	40	V
Forward Continuous Current	IFM	200	mA
Average rectified output current	Io	200	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	IFSM	0.6	A
Power Dissipation	PD	200	mW
Thermal Resistance from Junction to Ambient	R <sub>θJA</sub>	500	°C/W
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>TG</sub>	-55~+150	°C

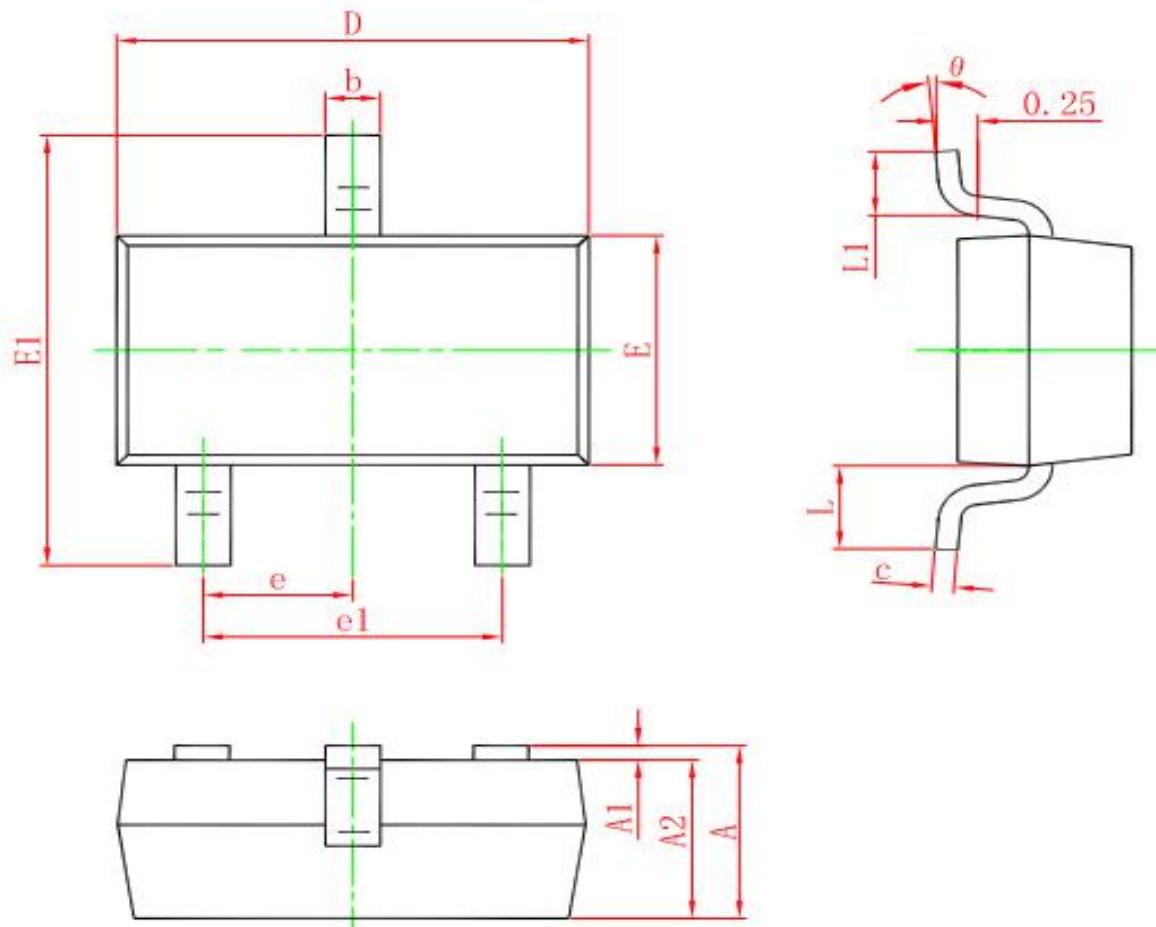
## Electrical Characteristics (@Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse breakdown voltage	V(BR)	IR=10μA	40			V
Forward voltage	VF1	IF=1mA			380	mV
	VF2	IF=40mA			1000	mV
Reverse voltage leakage current	IR	VR=30V			200	nA
Diode Capacitance	Ctot	VR=0V,f=1MHz			5	pF
Reverse recovery time	t <sub>rr</sub>	IF=IR=10mA, I <sub>rr</sub> =1mA, RL= 100Ω			5	nS

## Typical Characteristics



### SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
theta	0°	8°	0°	8°